

## AST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	372854	(plurality first second stack\$4 mount\$4 upper lower) with ((flipchip (flip afj chip) (semiconductor die chip ic electronic microelectronic microcomputer ram element (integrated adj circuit)) with (bump ball bga)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/18 08:07
L2	105347	(substrate board pcb carrier) with 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/18 08:08
L3	14517	2 same ((bond\$4 pad) same wire)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/18 08:08
L4	4501	(signal\$4 process\$4) same 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/18 08:09
L5	3144	(seal\$4 encasulat\$4 resin epoxy encase) and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/18 08:10
L6	1037	(nonvolatile memory microcomputer) and 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/18 08:45
L7	2	"6509638".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/18 08:45